

IN THE CLAIMS:

The following listing of claims will replace all prior versions, and listings, of the claims in the application:

1. (Currently amended) An apparatus for aligning and soldering connectors onto an edge of a printed circuit board, the apparatus comprising:
 - a base having a top surface, said top surface having a slot;
 - a first finger clamp attached to said top surface and located between a side of said base and a side of said slot; and
 - a claw coupled to said top surface via said first finger clamp, said claw having a top claw side and a bottom claw side;
 - ~~wherein said bottom claw side is adapted to constrain connectors onto a printed circuit board during a reflow soldering process; and~~
 - ~~wherein said slot is dimensioned to only house a printed circuit board having properly aligned connectors.~~
2. (Original) The apparatus of Claim 1, wherein said slot comprises a circuit board slot and a connector slot.
3. (Original) The apparatus of Claim 2, wherein said circuit board slot and said connector slot are adapted to house a circuit board having at least two straddle-mounted connectors.
4. (Original) The apparatus of Claim 1, wherein said first finger clamp has a finger portion.

5. (Original) The apparatus of Claim 4, wherein said top claw side has a finger indentation for receiving said finger portion.

6. (Original) The apparatus of Claim 1, wherein said first finger clamp comprises four finger clamps.

7. (Original) The apparatus of Claim 1, further comprising a second finger clamp attached to said top surface and located between a second side of said base opposing the surface side nearest to said first clamp and a second side of said slot opposing the slot side nearest to said first clamp.

8. (Currently amended) The apparatus of Claim 7, wherein said second clamp comprises a finger portion adapted to be in direct contact with the a-printed circuit board.

9. (Original) The apparatus of Claim 1, wherein said bottom claw side comprises a plurality of claw pins.

10. (Original) The apparatus of Claim 9, wherein said top surface comprises a plurality of pin holes adapted to receive said plurality of claw pins.

11. (Currently amended) The apparatus of Claim 1, wherein said bottom claw side comprises a notch adapted to house the connectors to be -mounted on the an-edge of the a-printed circuit board.

12. (Original) The apparatus of Claim 11, wherein said notch is adapted to house at least two straddle-mounted connectors.

13. (Original) The apparatus of Claim 1, wherein said slot is dimensioned to constrain the connectors from Y-axis displacement during the soldering process.

14. (Currently amended) The apparatus of Claim 13, wherein said bottom claw side constrains the connectors from Z-axis displacement during a ~~the~~ soldering process.

15. (Currently amended) The apparatus of Claim 1, wherein said apparatus is comprised of a heat resistant material comprising an epoxy-resin-glass fiber.

Claims 16-25(Cancelled).

26. (New) The apparatus of Claim 1, wherein said bottom claw side is adapted to constrain the connectors onto the printed circuit board during a reflow soldering process.

27. (New) The apparatus of Claim 1, wherein said slot is dimensioned to only house the printed circuit board when the connectors have been properly aligned to the printed circuit board.

28. (New) The apparatus of Claim 1, wherein said bottom claw side is adapted to constrain the connectors onto the printed circuit board during a reflow soldering process and wherein said slot is dimensioned to only house the printed circuit board when the connectors have been properly aligned to the printed circuit board.